

### SMD ■ REFLECTOR EAPL4040RA0

PRELIMINARY



#### Features

- Fluorescence Type
- High Luminous Intensity
- High Efficiency
- Pb-free.
- The product itself will remain with RoHS compliant version
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#### Applications

- OA Equipment
- Backlighting of Full Color LCD
- Replacement of Conventional Light
- Bulbs and Fluorescent Lamps

## Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Brilliant Red	Water Clear

## Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	IFP	60	mA
Power Dissipation	Pd	60	mW
Electrostatic Discharge(HBM)	ESD	2000	V
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~+100	°C
Soldering Temperature	Tsol	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

### Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I <sub>v</sub>	45	-----	112	mcd	I <sub>F</sub> =20mA
Viewing Angle	2θ <sub>1/2</sub>	-----	120	-----	deg	I <sub>F</sub> =20mA
Peak Wavelength	λ <sub>p</sub>	-----	632	-----	nm	I <sub>F</sub> =20mA
Dominant Wavelength	λ <sub>d</sub>	617.5	-----	633.5	nm	I <sub>F</sub> =20mA
Spectrum Radiation Bandwidth	Δλ	-----	20	-----	nm	I <sub>F</sub> =20mA
Forward Voltage	V <sub>F</sub>	1.75	-----	2.35	V	I <sub>F</sub> =20mA
Reverse Current	I <sub>R</sub>	-----	-----	10	μA	V <sub>R</sub> =5V

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.1V

### Bin Range of Luminous Intensity

Bin	Min	Max	Unit	Condition
P1	45	57	mcd	I <sub>F</sub> =20mA
P2	57	72		
Q1	72	90		
Q2	90	112		

Note:

Tolerance of Luminous Intensity: ±11%

### Bin Range of Dominant Wavelength

Group	Bin Code	Min.	Max.	Unit	Condition
A	E4	617.5	621.5	nm	IF=20mA
	E5	621.5	625.5		
	E6	625.5	629.5		
	E7	629.5	633.5		

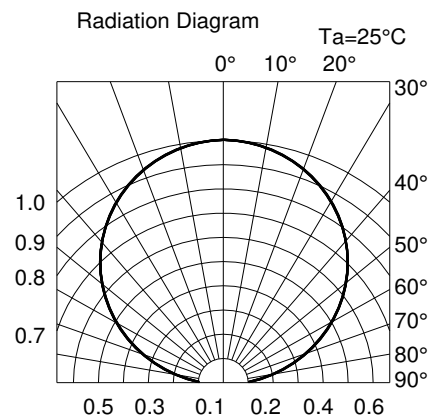
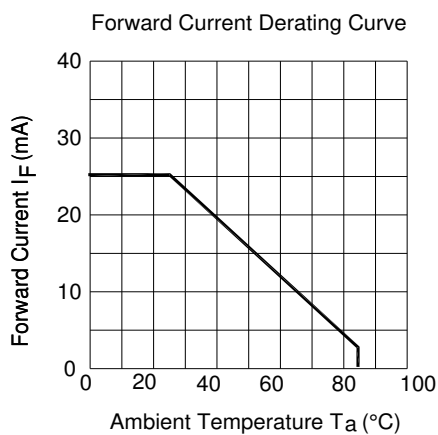
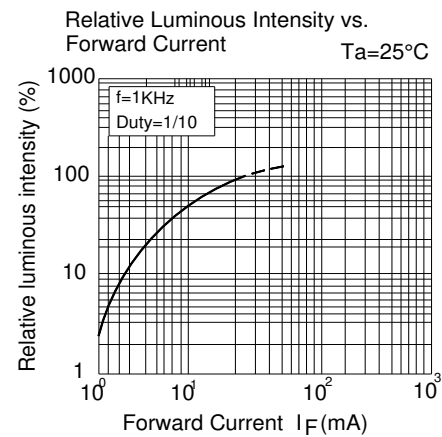
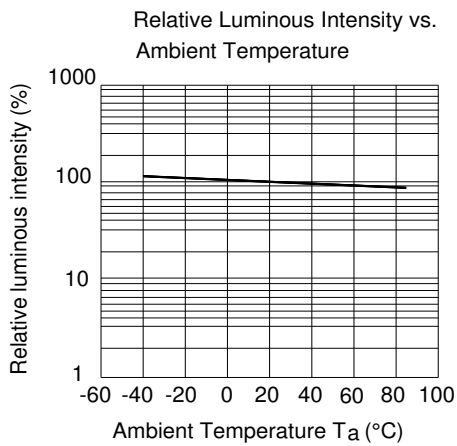
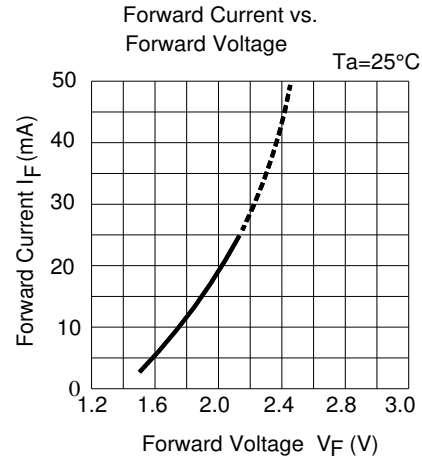
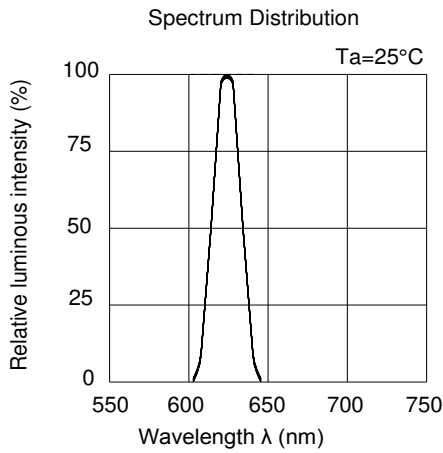
Note:  
 Tolerance of Dominant Wavelength:  $\pm 1\text{nm}$

### Bin Range of Forward Voltage

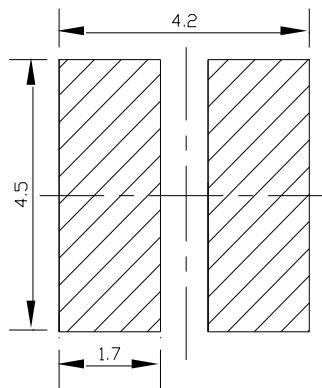
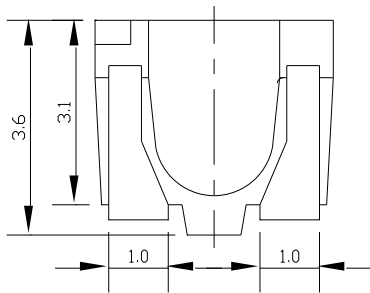
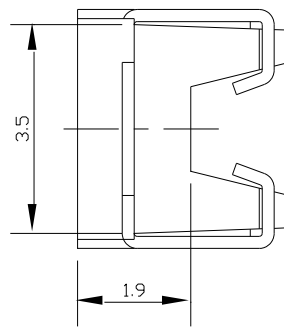
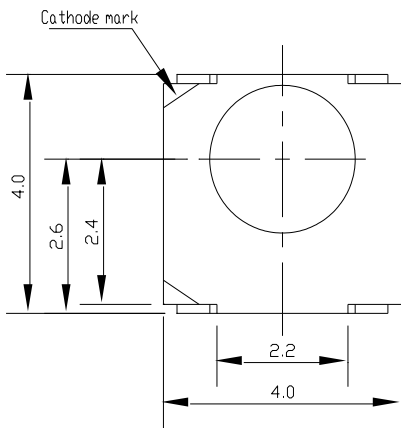
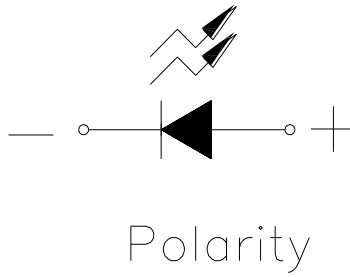
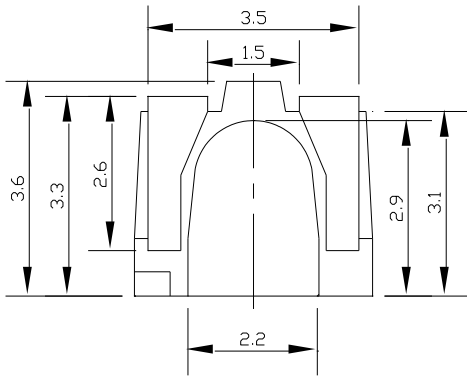
Group	Bin	Min	Max	Unit	Condition
B	0	1.75	1.95	V	IF=20mA
	1	1.95	2.15		
	2	2.15	2.35		

Note:  
 Tolerance of Forward Voltage  $\pm 0.1\text{V}$

## Typical Electro-Optical Characteristics Curves



**Package Dimension**

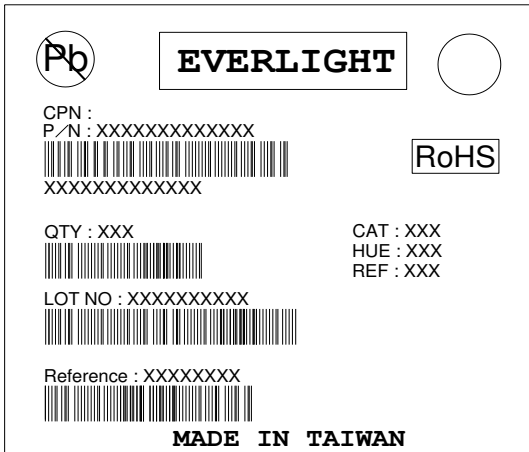


Recommended soldering pad design

Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

## Moisture Resistant Packing Materials

### Label Explanation

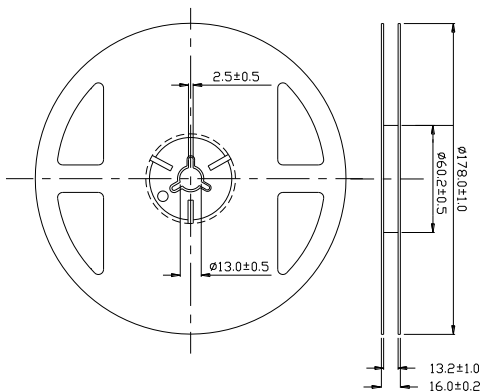


CAT: Luminous Intensity Rank

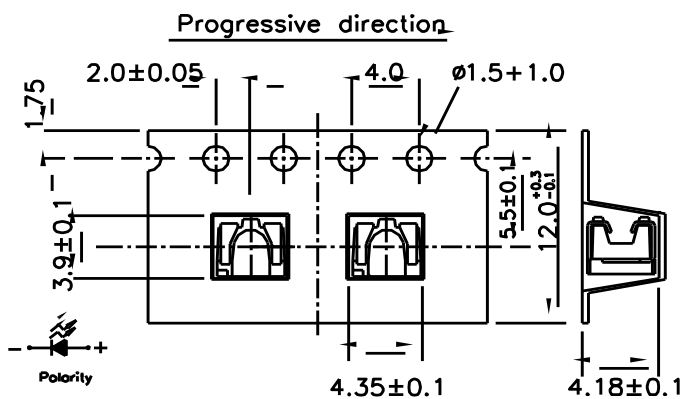
HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank

### Reel Dimensions

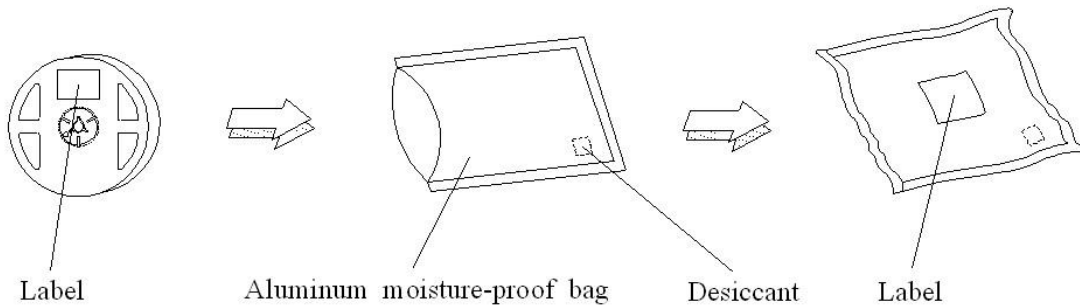


### Carrier Tape Dimensions: Loaded Quantity 500 pcs Per Reel



Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

### Moisture Resistant Packing Process



Note: Tolerances unless mentioned  $\pm 0.1\text{mm}$ . Unit = mm

### Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : $260^{\circ}\text{C}\pm 5^{\circ}\text{C}$ Min. 5sec.	6 min	22 PCS.	0/1
2	Temperature Cycle	H : $+100^{\circ}\text{C}$ 15min $\int$ 5 min L : $-40^{\circ}\text{C}$ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : $+100^{\circ}\text{C}$ 5min $\int$ 10 sec L : $-10^{\circ}\text{C}$ 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : $100^{\circ}\text{C}$	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : $-40^{\circ}\text{C}$	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	IF = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	$85^{\circ}\text{C} / 85\%\text{RH}$	1000 Hrs.	22 PCS.	0/1



## Precautions For Use

### 1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen ).

### 2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

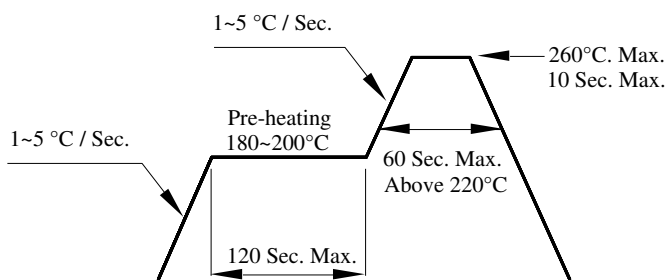
2.3 After opening the package: The LED's floor life is 48 hours under 30°C or less and 60% RH or less. If unused LEDs remain, should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

### 3. Soldering Condition

#### 3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

